

L Number	Hits	Search Text	DB	Time stamp
1	622	(semiconductor wafer) near blad	USPAT; US-PGPUB; EP ; JP ; DERWENT; IBM_TDB	2003/10/17 14:42
2	1399972	(semiconductor wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 14:42
3	110214	((semiconductor wafer) ) and sensor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 14:43
4	7687	((semiconductor wafer) ) and sensor) and strain	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 14:43
5	1985	((((semiconductor wafer) ) and sensor) and strain) and (piezoelectric piezo-electric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 14:44
6	7	(((((semiconductor wafer) ) and sensor) and strain) and (piezoelectric piezo-electric)) and 294/\$.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 14:54
7	35	("Re28663"   "1315581"   "3353860"   "3370213"   "3491520"   "3625378"   "3827437"   "4130314"   "4540211"   "4544193"   "4552397"   "4565400"   "4579380"   "4590673"   "4610475"   "4667997"   "4671553"   "4694230"   "4696501"   "4699414"   "4723806"   "4735451"   "4796357"   "4808898"   "4813732"   "4816730"   "4819978"   "4828309"   "4872803"   "4898416"   "4955656"   "4976484"   "5046773"   "5080415"   "5163804").PN.	USPAT	2003/10/17 14:49
8	13	((((semiconductor wafer) ) and sensor) and strain) and (piezoelectric piezo-electric)) and 414/\$.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 15:02
9	7	("4610475"   "4642438"   "4667997"   "5100502"   "5438419"   "5511931"   "5641264").PN.	USPAT	2003/10/17 14:59

10	50	(((((semiconductor wafer) ) and sensor) and strain) and (piezoelectric piezo-electric)) and 29/\$.ccls.	USPAT; US-PGPUB; EP; JPO; DERWENT; IBM_TDB USPAT	2003/10/17 15:14
11	10	("4674186"   "5266801"   "5325081"   "5345815"   "5386720"   "5400647"   "5468959"   "5469733"   "5907095"   "6072247").PN.		2003/10/17 15:06
12	502	(((((semiconductor wafer) ) and sensor) and strain) and (piezoelectric piezo-electric)) and 73/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 15:15
13	123	(((((semiconductor wafer) ) and sensor) and strain) and (piezoelectric piezo-electric)) and 73/\$.ccls.) and micro	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 15:15
-	1	chun-keng near hsu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 10:36
-	0	tin-hau near kuo	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 10:36
-	1	chun-chih near lin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 10:36
-	2	chao-lin near lee	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 10:37
-	432	wafer near blade	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 11:15
-	1128713	sensor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 13:30

-	3798	<b>sens r near strain</b>	<b>USPAT; US-P PUB; EP ; JP ; DERWENT; IBM_TDB</b>	<b>2002/11/04 10:38</b>
-	787	<b>(sensor near strain) and (piez electric r piezo-electric or piezo)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/11/04 10:39</b>
-	73	<b>(sensor near strain) near (piezoelectric or piezo-electric or piezo)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/11/04 10:39</b>
-	0	<b>(wafer near blade) and ((sensor near strain) and (piezoelectric or piezo-electric or piezo))</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/11/04 10:39</b>
-	134	<b>(wafer near blade) and sensor</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/11/04 10:39</b>
-	10	<b>((wafer near blade) and sensor) and (piezoelectric)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/11/04 11:15</b>
-	7	<b>("4610475"   "4642438"   "4667997"   "5100502"   "5438419"   "5511931"   "5641264").PN.</b>	<b>USPAT</b>	<b>2002/11/04 11:11</b>
-	3	<b>"6113165"</b>	<b>USPAT</b>	<b>2002/11/04 11:11</b>
-	21	<b>("4040736"   "4093378"   "5044752"   "5103367"   "5173832"   "5400209"   "5436790"   "5444342"   "5444597"   "5445486"   "5556147"   "5645391"   "5669752"   "5841515"   "5842491"   "5863170"   "5867359"   "5872694"   "5885355"   "5903123"   "5948986").PN.</b>	<b>USPAT</b>	<b>2002/11/04 11:11</b>
-	4471	<b>wafer near chuck</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/11/04 11:15</b>
-	170	<b>(wafer near chuck) and (piezoelectric)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/11/04 11:15</b>

-	97	((wafer near chuck) and (piezoelectric)) and sensor	USPAT; US-P PUB; EP ; JPO; DERWENT; IBM_TDB	2002/11/04 11:16
-	77	((wafer near chuck) and (piezoelectric)) and sensor ) and (alarm signal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 13:23
-	3	((wafer near chuck) and (piezoelectric)) and sensor ) and (alarm)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 13:24
-	134	(wafer near blade) and sensor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 13:30
-	7	((wafer near blade) and sensor ) and alarm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 13:30
-	5358	strain near gage	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 14:56
-	878	(strain near gage) and (wafer semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 14:56
-	1424	(strain near (sensor or gage)) and (wafer semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 14:57
-	68	(strain near (sensor or gage)) and (wafer semiconductor) and blade	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 14:58
-	2	("6494882").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:45

-	28565	strain near (sensor gauge)	USPAT; US-PGPUB; EP ; JP ; DERWENT; IBM_TDB	2003/08/12 12:46
-	605	(wafer semiconductor) near blade	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:46
-	465244	thin same film	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:46
-	4	(strain near (sensor gauge)) and ((wafer semiconductor) near blade)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:48
-	5807	piezoelectric near (sensor sensing sensitive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:49
-	584	(strain near (sensor gauge)) and (piezoelectric near (sensor sensing sensitive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:50
-	5	("4502857"   "5043111"   "5174933"   "5528452"   "6294113").PN.	USPAT	2003/08/12 13:31
-	145	(73/767).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 13:13
-	17035	sensitivity and 73/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 13:16
-	468	(sensitivity and 73/\$.ccls.) and (strain near sensor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 13:15
-	162268	73/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 15:56

-	4339	<b>strain near sens r</b>	<b>USPAT; US-P PUB; EP ; JP ; DERWENT; IBM_TDB</b>	<b>2003/08/25 13:15</b>
-	975	<b>73/\$.ccls. and (strain near sensor)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 13:15</b>
-	468	<b>sensitivity and (73/\$.ccls. and (strain near sensor))</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 13:42</b>
-	18832	<b>(touch contact) near sensor</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 16:06</b>
-	46	<b>(73/\$.ccls. and (strain near sensor)) and ((touch contact) near sensor)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 13:43</b>
-	928	<b>((touch contact) near sensor) and micron</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 15:56</b>
-	10	<b>(strain near sensor) and (((touch contact) near sensor) and micron)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 13:52</b>
-	77270	<b>414/\$.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 16:06</b>
-	22990	<b>(strain touch contact) near sensor</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 15:57</b>
-	220	<b>414/\$.ccls. and ((strain touch contact) near sensor)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 16:11</b>

-	5	<b>(414/\$.ccls. and ((strain touch contact) near sensor) and micron</b>	<b>USPAT; US-P PUB; EP ; JP ; DERWENT; IBM_TDB</b>	<b>2003/08/25 15:58</b>
-	12	<b>("4449885"   "4520421"   "4565601"   "4743570"   "4892451"   "4911597"   "4962441"   "4999507"   "5007981"   "5113992"   "5258047"   "5315473").PN.</b>	<b>USPAT</b>	<b>2003/08/25 16:03</b>
-	36806	<b>294/\$.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 16:06</b>
-	51	<b>294/\$.ccls. and ((strain touch contact) near sensor)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 16:10</b>
-	5822	<b>wafer near (blade chuck gripper)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 16:11</b>
-	49	<b>(wafer near (blade chuck gripper)) and ((strain touch contact) near sensor)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 16:11</b>
-	29618	<b>strain near (sensor gauge)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 17:33</b>
-	5606	<b>sensitivity same micron</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 17:33</b>
-	94	<b>(strain near (sensor gauge)) and (sensitivity same micron)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 17:38</b>
-	116	<b>(73/768).CCLS.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 17:56</b>

-	524	<b>piezo- lectric near sens r</b>	<b>USPAT; US-PGPUB; EP ; JP ; DERWENT; IBM_TDB</b>	<b>2003/08/25 17:48</b>
-	60	<b>(strain near (sensor gauge)) and (piezo-electric near sensor)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 17:48</b>
-	1	<b>((strain near (sensor gauge)) and (piezo-electric near sensor)) and micron</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 17:43</b>
-	5260	<b>piezoelectric near sensor</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 17:48</b>
-	578	<b>(strain near (sensor gauge)) and (piezoelectric near sensor)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 17:48</b>
-	143	<b>((strain near (sensor gauge)) and (piezoelectric near sensor)) and (semiconductor wafer)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 17:49</b>
-	145	<b>(73/769).CCLS.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 18:17</b>
-	60	<b>(73/770).CCLS.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 18:17</b>